



## MODULE SPECIFICATION

Part 1: Information			
Module Title	High Speed Electronic System Design		
Module Code	UFMFUN-15-M	Level	Level 7
For implementation from	2018-19		
UWE Credit Rating	15	ECTS Credit Rating	7.5
Faculty	Faculty of Environment & Technology	Field	Engineering, Design and Mathematics
Department	FET Dept of Engin Design & Mathematics		
Contributes towards			
Module type:	Standard		
Pre-requisites	None		
Excluded Combinations	None		
Co- requisites	None		
Module Entry requirements	None		

Part 2: Description
<p><b>Overview:</b> The module provides a systematic view of the performance limitations related to high-speed electronic systems and their dependencies on the underlying technology choices. The key focus is how the interconnects (wires), all the way from system level to chip-level affect the system performance and how it will define the performance, reliability and the price of the end-product. The students will develop a thorough theoretical basis of the fundamental system level electrical issues and gain experience to design, simulate, and analyse electronic circuits.</p> <p><b>Educational Aims:</b> This module will extend and further develop the practical, theoretical and professional skills needed for designing and implementing complex digital systems for a wide range of applications.</p> <p><b>Outline Syllabus:</b> The syllabus includes the following topics:</p> <p>Interconnect modelling: wires, Connectors, Vias, and Solder Bumps</p>

## STUDENT AND ACADEMIC SERVICES

Signal Integrity Issues in Electronic Systems

Power Supply Noise and Power Delivery Systems

EMC/EMI Fundamentals in Electronic Systems

Shielding and Electrostatic Discharge (ESD) Protection

Thermal Design in Electronic System

Production and Disposal of Electronic Systems

**Teaching and Learning Methods:** An initial set of structured laboratory exercises will extend the students understanding of the tools and techniques required, followed by a problem based exercise. These exercises will provide the basis for the assessed coursework and for the laboratory exams.

### Part 3: Assessment

Summative assessment will be achieved through

(Component A). Will involve a presentation on a case study that will assess the student's ability to correctly understand and predict performance limitations factors in high speed electronic circuits. The presentation will be for 15 minutes followed by questions.

(Component B) Students will undertake a series of practical design, simulation and implementation tasks based on laboratory work. Students will select four tasks to submit as part of portfolio. Each task will lead to a short report (500 words) where students evaluate and reflect on their design solutions. The reports will form a portfolio (2,000 words).

Formative feedback will provided through verbal feedback during laboratory sessions and through tutorial exercises.

First Sit Components	Final Assessment	Element weighting	Description
Portfolio - Component B		75 %	Design portfolio (2,000 words)
Presentation - Component A	✓	25 %	Individual Presentation (15 minutes)
Resit Components	Final Assessment	Element weighting	Description
Portfolio - Component B		75 %	Design portfolio (2,000 words)
Presentation - Component A	✓	25 %	Individual presentation (15 minutes)

STUDENT AND ACADEMIC SERVICES

<b>Part 4: Teaching and Learning Methods</b>		
Learning Outcomes	On successful completion of this module students will be able to:	
	<b>Module Learning Outcomes</b>	
	MO1	Use quantitative methods and appropriate computer software tools to design complex electronic systems from printed circuits board (PCB) level to higher levels
	MO2	Explain and apply basic principles and design guidelines to complex electronic systems
	MO3	Identify and manage cost drivers in the design and development of electronic systems and model the performance of electronic system
	MO4	Apply analytical methods (i.e. circuit theory) and modelling techniques (i.e. electronic device models) to the identification, classification and description of electronic circuits and their performance in response to a range of externally applied stimuli.
	MO5	Analyse systematically the key electrical phenomena at interconnection substrate levels defining the system signal integrity and robustness properties in order to define the future constraints to integration for consumer electronic products.
Contact Hours	<b>Contact Hours</b>	
	<b>Independent Study Hours:</b>	
	Independent study/self-guided study	126
	<b>Total Independent Study Hours:</b>	126
	<b>Scheduled Learning and Teaching Hours:</b>	
	Face-to-face learning	24
	<b>Total Scheduled Learning and Teaching Hours:</b>	24
	<b>Hours to be allocated</b>	150
	<b>Allocated Hours</b>	150
Reading List	<p>The reading list for this module can be accessed via the following link:</p> <p><a href="https://uwe.rl.talis.com/modules/ufmfun-15-m.html">https://uwe.rl.talis.com/modules/ufmfun-15-m.html</a></p>	